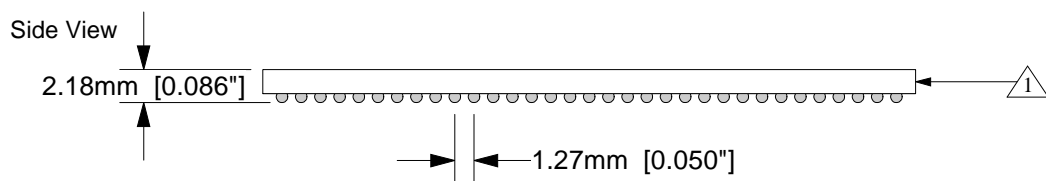



Bottom View




 Substrate: 1.59mm  $\pm$ 0.18mm [0.0625"  $\pm$ 0.007"]  
FR4/G10 or equivalent high temp material. 17 $\mu$ m [1/2 oz.] Cu clad. SnPb plating.

Description: Device Converter

241 position BGA land pattern to 560 position BGA base. Converts Intel 82801AA to Xilinx Virtex as per Standard Microsystem's specifications.

Tolerances: diameters  $\pm$ 0.03mm [ $\pm$ 0.001"],  
PCB perimeters  $\pm$ 0.13mm [ $\pm$ 0.005"],  
PCB thicknesses  $\pm$ 0.18mm [ $\pm$ 0.007"],  
itches (from true position)  $\pm$ 0.08mm [ $\pm$ 0.003"],

all other tolerances  $\pm$ 0.13mm [ $\pm$ 0.005"]  
unless stated otherwise. Materials and specifications are subject to change without notice.

	<b>DC-BGA/BGA-82801-S-B-01 Drawing</b>		Status: Released	Scale: 2:1	Rev: A
	© 2001 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com			Drawing: D Megran	
				Date: 2/2/01	
			File: DC-BGA_BGA-82801-S-B-01 Dwg.mcd		Modified: